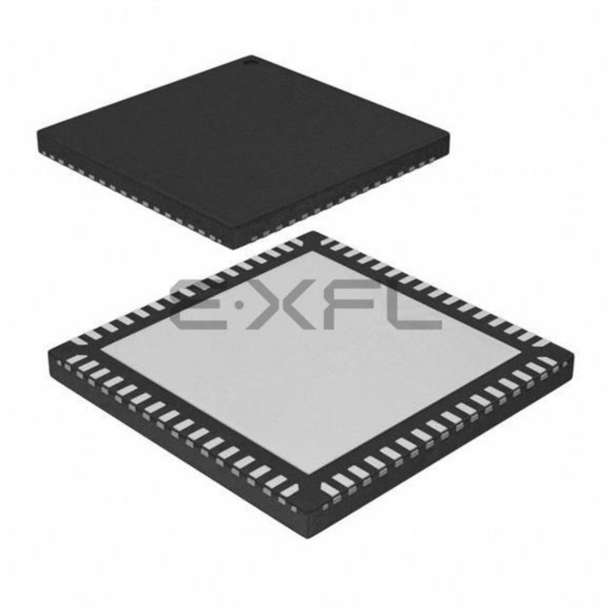

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	56
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32g840f32-qfn64

  - Supply Voltage Comparator
- Ultra efficient Power-on Reset and Brown-Out Detector
- 2-pin Serial Wire Debug Interface
  - 1-pin Serial Wire Viewer
- Pre-Programmed USB/UART Bootloader
- Temperature range -40 to 85 ºC
- Single power supply 1.98 to 3.8 V
- Packages
  - BGA112
  - LQFP100
  - TQFP64
  - TQFP48
  - QFN64
  - QFN32

2. Ordering Information

The following table shows the available EFM32G devices.

Table 2.1. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (ºC)	Package
EFM32G200F16G-E-QFN32	16	8	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G200F32G-E-QFN32	32	8	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G200F64G-E-QFN32	64	16	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G210F128G-E-QFN32	128	16	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G222F32G-E-QFP48	32	8	32	1.98 - 3.8	-40 - 85	TQFP48
EFM32G222F64G-E-QFP48	64	16	32	1.98 - 3.8	-40 - 85	TQFP48
EFM32G222F128G-E-QFP48	128	16	32	1.98 - 3.8	-40 - 85	TQFP48
EFM32G230F32G-E-QFN64	32	8	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G230F64G-E-QFN64	64	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G230F128G-E-QFN64	128	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G232F32G-E-QFP64	32	8	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G232F64G-E-QFP64	64	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G232F128G-E-QFP64	128	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G280F32G-E-QFP100	32	8	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G280F64G-E-QFP100	64	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G280F128G-E-QFP100	128	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G290F32G-E-BGA112	32	8	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G290F64G-E-BGA112	64	16	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G290F128G-E-BGA112	128	16	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G840F32G-E-QFN64	32	8	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G840F64G-E-QFN64	64	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G840F128G-E-QFN64	128	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G842F32G-E-QFP64	32	8	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G842F64G-E-QFP64	64	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G842F128G-E-QFP64	128	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G880F32G-E-QFP100	32	8	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G880F64G-E-QFP100	64	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G880F128G-E-QFP100	128	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G890F32G-E-BGA112	32	8	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G890F64G-E-BGA112	64	16	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G890F128G-E-BGA112	128	16	32	1.98 - 3.8	-40 - 85	BGA112

3.1.4 Direct Memory Access Controller (DMA)

The Direct Memory Access (DMA) controller performs memory operations independently of the CPU. This has the benefit of reducing the energy consumption and the workload of the CPU, and enables the system to stay in low energy modes when moving for instance data from the USART to RAM or from the External Bus Interface to a PWM-generating timer. The DMA controller uses the PL230 µDMA controller licensed from ARM.

3.1.5 Reset Management Unit (RMU)

The RMU is responsible for handling the reset functionality of the EFM32G.

3.1.6 Energy Management Unit (EMU)

The Energy Management Unit (EMU) manage all the low energy modes (EM) in EFM32G microcontrollers. Each energy mode manages if the CPU and the various peripherals are available. The EMU can also be used to turn off the power to unused SRAM blocks.

3.1.7 Clock Management Unit (CMU)

The Clock Management Unit (CMU) is responsible for controlling the oscillators and clocks on-board the EFM32G. The CMU provides the capability to turn on and off the clock on an individual basis to all peripheral modules in addition to enable/disable and configure the available oscillators. The high degree of flexibility enables software to minimize energy consumption in any specific application by not wasting power on peripherals and oscillators that are inactive.

3.1.8 Watchdog (WDOG)

The purpose of the watchdog timer is to generate a reset in case of a system failure, to increase application reliability. The failure may e.g. be caused by an external event, such as an ESD pulse, or by a software failure.

3.1.9 Peripheral Reflex System (PRS)

The Peripheral Reflex System (PRS) system is a network which lets the different peripheral module communicate directly with each other without involving the CPU. Peripheral modules which send out Reflex signals are called producers. The PRS routes these reflex signals to consumer peripherals which apply actions depending on the data received. The format for the Reflex signals is not given, but edge triggers and other functionality can be applied by the PRS.

3.1.10 External Bus Interface (EBI)

The External Bus Interface provides access to external parallel interface devices such as SRAM, FLASH, ADCs and LCDs. The interface is memory mapped into the address bus of the Cortex-M3. This enables seamless access from software without manually manipulating the IO settings each time a read or write is performed. The data and address lines are multiplexed in order to reduce the number of pins required to interface the external devices. The timing is adjustable to meet specifications of the external devices. The interface is limited to asynchronous devices.

3.1.11 Inter-Integrated Circuit Interface (I2C)

The I^2C module provides an interface between the MCU and a serial I^2C-bus. It is capable of acting as both a master and a slave, and supports multi-master buses. Both standard-mode, fast-mode and fastmode plus speeds are supported, allowing transmission rates all the way from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also provided to allow implementation of an SMBus compliant system. The interface provided to software by the I^2C module, allows both fine-grained control of the transmission process and close to automatic transfers. Automatic recognition of slave addresses is provided in all energy modes.

3.1.12 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous Asynchronous serial Receiver and Transmitter (USART) is a very flexible serial I/O module. It supports full duplex asynchronous UART communication as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with ISO7816 SmartCards, and IrDA devices.

3.1.13 Pre-Programmed USB/UART Bootloader

The bootloader presented in application note AN0003 is pre-programmed in the device at factory. Autobaud and destructive write are supported. The autobaud feature, interface and commands are described further in the application note.

3.2 Configuration Summary

3.2.1 EFM32G200

The features of the EFM32G200 is a subset of the feature set described in the EFM32G Reference Manual. The following table describes device specific implementation of the features.

Table 3.1. EFM32G200 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration	US1_TX, US1_RX, US1_CLK, US1_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
RTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 8-bit count register	PCNT0_S[1:0]
ACMP0	Full configuration	ACMP0_CH[1:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:5], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:4]
DAC0	Full configuration	DAC0_OUT[0]
GPIO	24 pins	Available pins are shown in Table 4.3 (p. 57)

3.2.6 EFM32G280

The features of the EFM32G280 is a subset of the feature set described in the EFM32G Reference Manual. The following table describes device specific implementation of the features.

Table 3.6. EFM32G280 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
EBI	Full configuration	EBI_ARDY, EBI_ALE, EBI_WEn, EBI_REn, EBI_CS[3:0], EBI_AD[15:0]
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX. US0_CLK, US0_CS
USART1	Full configuration	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration	US2_TX, US2_RX, US2_CLK, US2_CS
UART0	Full configuration	U0_TX, U0_RX
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 8-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0]
AES	Full configuration	NA
GPIO	86 pins	Available pins are shown in Table 4.3 (p. 57)

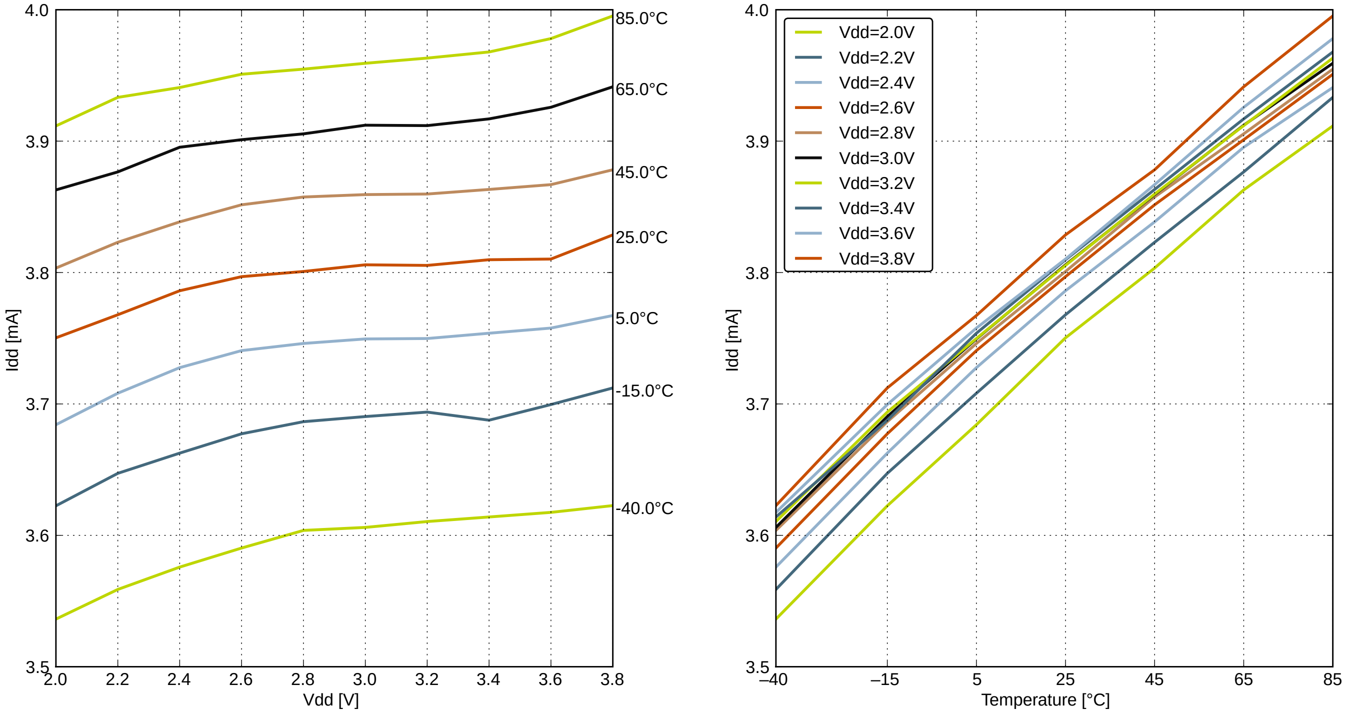

Figure 4.2. EM0 Current consumption while executing prime number calculation code from flash with HFRCO running at 21 MHz

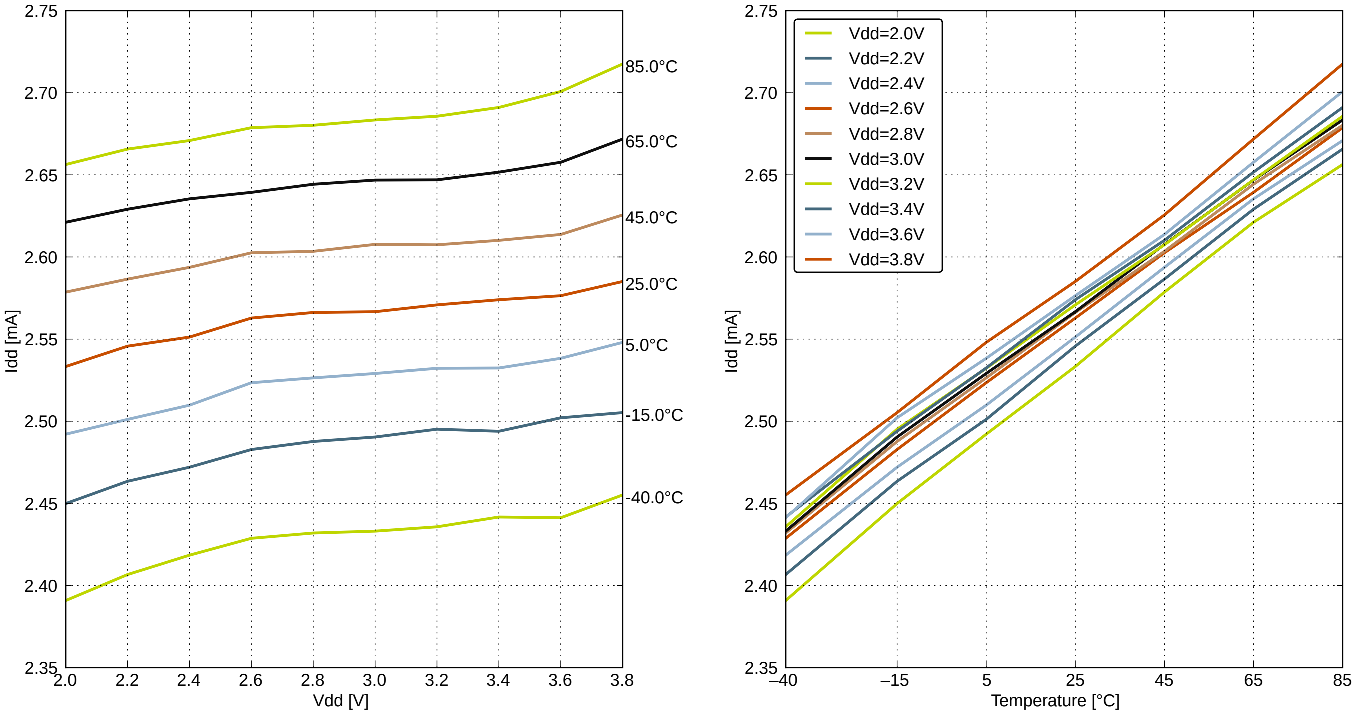

Figure 4.3. EM0 Current consumption while executing prime number calculation code from flash with HFRCO running at 14 MHz

4.7 Flash

Table 4.6. Flash

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		20000	—	—	cycles
Flash data retention	RET_{FLASH}	T_{AMB}<150 ºC	10000	—	—	h
		T_{AMB}<85 ºC	10	—	—	years
		T_{AMB}<70 ºC	20	—	—	years
Word (32-bit) programming time	t_{W_PROG}		20	—	—	µs
Page erase time[2]	t_{P_ERASE}		20.7	22.0	24.8	ms
Device erase time[3]	t_{D_ERASE}		41.8	45.0	49.2	ms
Erase current	I_{ERASE}		—	—	7[1]	mA
Write current	I_{WRITE}		—	—	7[1]	mA
Supply voltage during flash erase and write	V_{FLASH}		1.98	—	3.8	V

Note:

1. Measured at 25 °C.
2. From setting ERASEPAGE bit in MSC_WRITECMD to 1 to reading 1 in ERASE bit in MSC_IF. Internal setup and hold times for flash control signals are included.
3. From setting DEVICEERASE bit in AAP_CMD to 1 to reading 0 in ERASEBUSY bit in AAP_STATUS. Internal setup and hold times for flash control signals are included.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise Ratio (SNR)	SNR_{ADC}	200 kSamples/s, 12 bit, differential, V_{DD} reference,ADC_CLK = 7 MHz, BIASPROG = 0x747	63	69	—	dB
		200 kSamples/s, 12 bit, differential, $2xV_{DD}$ reference,ADC_CLK = 7 MHz, BIASPROG = 0x747	—	70	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Signal-to-Noise And Distortion Ratio (SINAD)	$\mathrm{SINAD_{ADC}}$	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	58	—	dB
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	62	—	dB
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	63	—	dB
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	66	—	dB
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	62	68	—	dB
		1 MSamples/s, 12 bit, differential, 2xV_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	68	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	61	—	dB
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	62	—	dB
		200 kSamples/s, 12 bit, single-ended, VDD reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	63	—	dB
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	66	—	dB
		200 kSamples/s, 12 bit, differential, 5V reference, ADC_CLK= 7 MHz, BIASPROG = 0x747	—	66	—	dB

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range (SFDR)	$SFDR_{ADC}$	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	75	—	dBc
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	78	—	dBc
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	77	—	dBc
		1 MSamples/s, 12 bit, differential, V_{DD} reference, ADC_CLK= 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, $2xV_{DD}$ reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	68	79	—	dBc
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK =13 MHz, BIASPROG = 0xF4B	—	79	—	dBc
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	75	—	dBc
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	75	—	dBc
		200 kSamples/s, 12 bit, single-ended, V_{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	76	—	dBc
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	78	—	dBc

5.3.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32G230 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.9. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	—	—	—	—	PA10	PA8	PA8 —	—	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	—	PB14	PB13	PB12	PB11	—	—	PB8	PB7	—	—	—	—	—	—	—
Port C	PC15	PC14	PC13	PC12	PC11	PC10	PC9	PC8	PC7	PC6	PC5	PC4	PC3	PC2	PC1	PC0
Port D	—	—	—	—	—	—	—	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	—	—	—	—	—	—	—	—
Port F	—	—	—	—	—	—	—	—	—	—	PF5	PF4	PF3	PF2	PF1	PF0

Alternate	LOCATION				
Functionality	0	1	2	3	Description
TIM0_CDTI1	PA4	PC14	PF4	PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10	PB0		Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11	PB1		Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2		Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8		Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9		Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10		Timer 2 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15	UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9		USART0 clock input / output.
US0_CS	PE13	PE4	PC8		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
US1_RX	PC1	PD1			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0			USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5			USART2 clock input / output.
US2_CS	PC5	PB6			USART2 chip select input / output.
US2_RX	PC3	PB4			USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3			USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	**Pin Name**	**Analog**	**EBI**	**Timers**	**Communication**	**Other**
C3	PE10	LCD_SEG 6	EBI_AD02 #0	TIM1_CC0 #1	US0_TX #0	BOOT_TX
C4	PD13					
C5	PD12	LCD_SEG 31	EBI_CS3 #0			
C6	PF9	LCD_SEG 27				
C7	VSS	Ground.				
C8	PF2	LCD_SEG 0	EBI_ARDY #0			ACMP1_O #0 DBG_SWO #0
C9	PE6	LCD_COM 2			US0_RX #1	
C10	PC10	ACMP1_CH2		TIM2_CC2 #2	US0_RX #2	
C11	PC11	ACMP1_CH3			US0_TX #2	
D1	PA3	LCD_SEG 16	EBI_AD12 #0	TIM0_CDTI0 #0	U0_TX #2	
D2	PA2	LCD_SEG 15	EBI_AD11 #0	TIM0_CC2 #0/1		CMU_CLK0 #0
D3	PB15					
D4	VSS	Ground.				
D5	IOVDD_6	Digital IO power supply 6.				
D6	PD9	LCD_SEG 28	EBI_CS0 #0			
D7	IOVDD_5	Digital IO power supply 5.				
D8	PF1			LETIM0_OUT1 #2		DBG_SWDIO #0/1
D9	PE7	LCD_COM 3			US0_TX #1	
D10	PC8	ACMP1_CH0		TIM2_CC0 #2	US0_CS #2	
D11	PC9	ACMP1_CH1		TIM2_CC1 #2	US0_CLK #2	
E1	PA6	LCD_SEG 19	EBI_AD15 #0		LEU1_RX #1	
E2	PA5	LCD_SEG 18	EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
E3	PA4	LCD_SEG 17	EBI_AD13 #0	TIM0_CDTI1 #0	U0_RX #2	
E4	PB0	LCD_SEG 32		TIM1_CC0 #2		
E8	PF0			LETIM0_OUT0 #2		DBG_SWCLK #0/1

Alternate	LOCATION				
Functionality	0	1	2	3	Description
TIM0_CDTI1	PA4	PC14	PF4	PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	Timer 0 Complimentary Deat Time Insertion channel 2.
TIM1_CC0	PC13	PE10	PB0		Timer 1 Capture Compare input / output channel 0.
TIM1_CC1	PC14	PE11	PB1		Timer 1 Capture Compare input / output channel 1.
TIM1_CC2	PC15	PE12	PB2		Timer 1 Capture Compare input / output channel 2.
TIM2_CC0	PA8	PA12	PC8		Timer 2 Capture Compare input / output channel 0.
TIM2_CC1	PA9	PA13	PC9		Timer 2 Capture Compare input / output channel 1.
TIM2_CC2	PA10	PA14	PC10		Timer 2 Capture Compare input / output channel 2.
U0_RX	PF7	PE1	PA4	PC15	UART0 Receive input.
U0_TX	PF6	PE0	PA3	PC14	UART0 Transmit output. Also used as receive input in half duplex communication.
US0_CLK	PE12	PE5	PC9		USART0 clock input / output.
US0_CS	PE13	PE4	PC8		USART0 chip select input / output.
US0_RX	PE11	PE6	PC10		USART0 Asynchronous Receive. USART0 Synchronous mode Master Input / Slave Output (MISO).
US0_TX	PE10	PE7	PC11		USART0 Asynchronous Transmit.Also used as receive input in half duplex communication. USART0 Synchronous mode Master Output / Slave Input (MOSI).
US1_CLK	PB7	PD2			USART1 clock input / output.
US1_CS	PB8	PD3			USART1 chip select input / output.
US1_RX	PC1	PD1			USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	PC0	PD0			USART1 Asynchronous Transmit.Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	PC4	PB5			USART2 clock input / output.
US2_CS	PC5	PB6			USART2 chip select input / output.
US2_RX	PC3	PB4			USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	PC2	PB3			USART2 Asynchronous Transmit.Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).

6.2 BGA112 PCB Layout

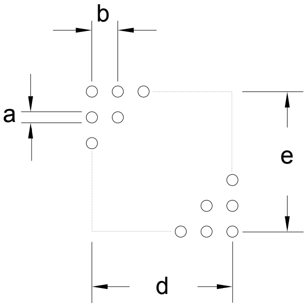

Figure 6.2. BGA112 PCB Land Pattern

Table 6.1. BGA112 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.35
b	0.80
d	8.00
e	8.00

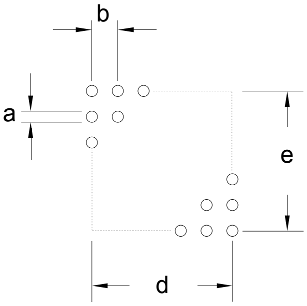

Figure 6.3. BGA112 PCB Solder Mask

Table 6.2. BGA112 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.48
b	0.80
d	8.00
e	8.00

DIM	MIN	NOM	MAX	DIM	MIN	NOM	MAX
b	0.17	0.22	0.27	S	0.20	—	—
b1	0.17	0.20	0.23	θ	0°	3.5°	7°
c	0.09	—	0.20	θ1	0°	—	—
C1	0.09	—	0.16	θ2	11°	12°	13°
D	12.0 BSC			θ3	11°	12°	13°
D1	10.0 BSC						
e	0.50 BSC						
E	12.0 BSC						
E1	10.0 BSC						
L	0.45	0.60	0.75				

The TQFP64 Package is 10 by 10 mm in size and has a 0.5 mm pin pitch.

The TQFP64 Package uses Nickel-Palladium-Gold preplated leadframe.

All EFM32 packages are RoHS compliant and free of Bromine (Br) and Antimony (Sb).

For additional Quality and Environmental information, please see: http://www.silabs.com/support/quality/pages/default.aspx.

9.2 TQFP48 PCB Layout

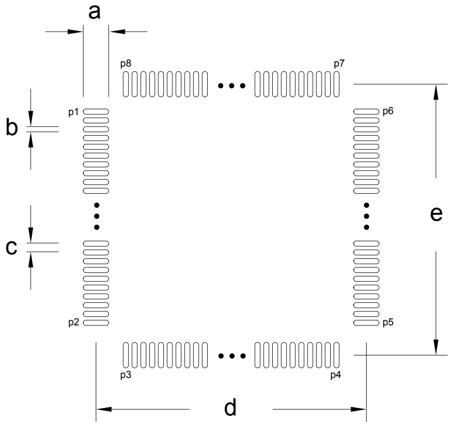

Figure 9.2. TQFP48 PCB Land Pattern

Table 9.2. TQFP48 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	1.60	P1	1	P6	36
b	0.30	P2	12	P7	37
c	0.50	P3	13	P8	48
d	8.50	P4	24		
e	8.50	P5	25		

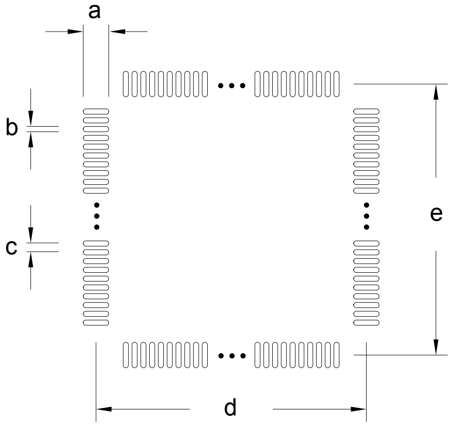

Figure 9.3. TQFP48 PCB Solder Mask

Table 9.3. TQFP48 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	1.72
b	0.42
c	0.50
d	8.50
e	8.50

10.2 QFN64 PCB Layout

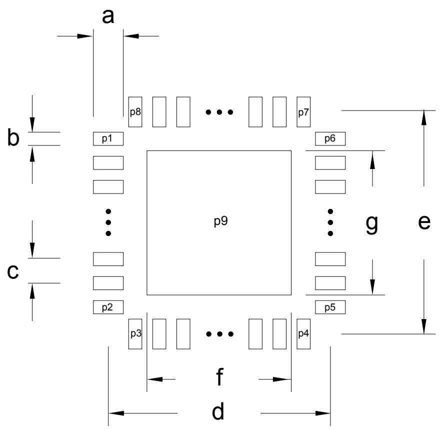

Figure 10.2. QFN64 PCB Land Pattern

Table 10.2. QFN64 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	0.85	P1	1	P8	64
b	0.30	P2	16	P9	65
c	0.50	P3	17		
d	8.90	P4	32		
e	8.90	P5	33		
f	7.20	P6	48		
g	7.20	P7	49		

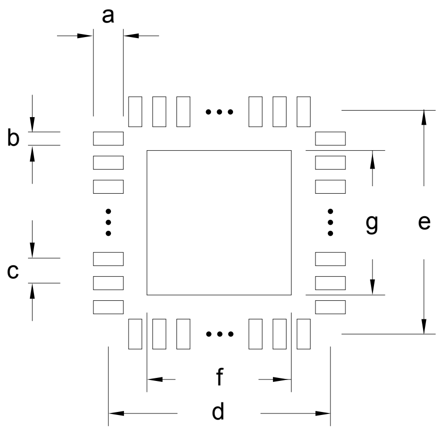

Figure 10.3. QFN64 PCB Solder Mask

Table 10.3. QFN64 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Dim. (mm)
a	0.97	e	8.90
b	0.42	f	7.32
c	0.50	g	7.32

11.2 QFN32 PCB Layout

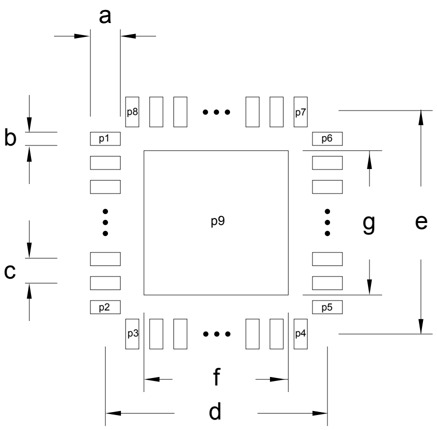

Figure 11.2. QFN32 PCB Land Pattern

Table 11.2. QFN32 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	0.80	P1	1	P6	24
b	0.35	P2	8	P7	25
c	0.65	P3	9	P8	32
d	6.00	P4	16	P9	33
e	6.00	P5	17		
f	4.40				
g	4.40				

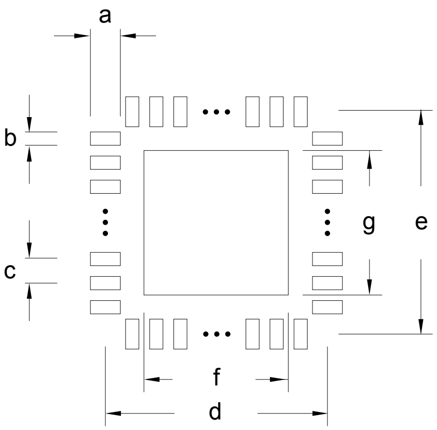

Figure 11.3. QFN32 PCB Solder Mask

Table 11.3. QFN32 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	0.92
b	0.47
c	0.65

11.3 QFN32 Package Marking

In the illustration below package fields and position are shown.

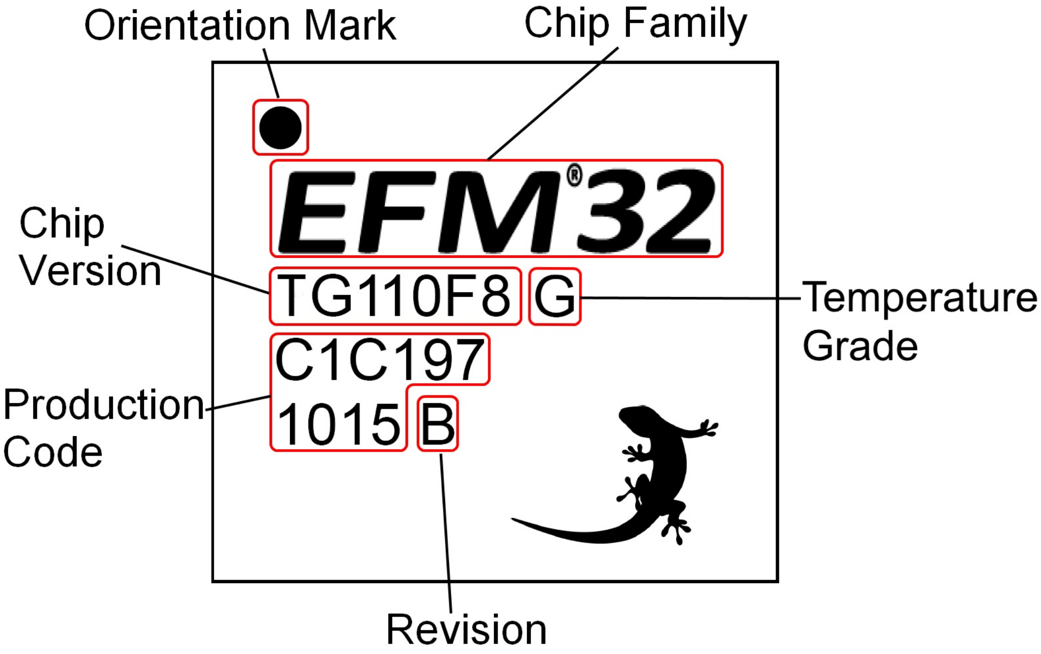

Figure 11.5. Example Chip Marking (Top View)